



2814

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

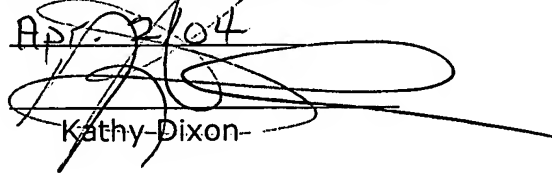
**APPLICANT:** Kuo-Yu Chou  
**SERIAL NO.:** 10/043,709  
**FILED:** 01/09/2002  
**TITLED:** A SINGLE LAYER WIRING BOND PAD WITH OPTIMUM AL FILM THICKNESS  
IN CU/FSG PROCESS FOR DEVICES UNDER PADS

**EXAMINER:** Le, Thao X.  
**ART UNIT:** 2814  
**ATTY DKT NO.:** 67,200-603

**CERTIFICATE OF MAILING**

**Please forward all correspondence to:**  
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**RESPONSE UNDER 37 C.F.R. §1.111**

Dear Sir:

In response to the Office Action dated January 5, 2004 (Paper No. 1203) in  
the above captioned matter, please enter the following remarks: